imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

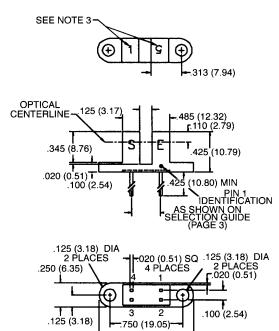
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QVB SERIES

PACKAGE DIMENSIONS



COLLECTOR 3

.971 (24.64)

ST2175

NOTES:

- 1. DIMENSIONS ARE IN INCHES (mm).
- 2. TOLERANCE IS ±.010 (.25)
- UNLESS OTHERWISE SPECIFIED. 3. NUMBER INDICATES APERTURE SIZE.
- (5 = .050'', 1 = .010'')

DESCRIPTION

The QVB series of switches is designed to allow the user maximum flexibility in applications. Each switch consists of an infrared emitting diode facing an NPN phototransistor across a .125" (3.18 mm) gap. A unique housing design provides a smooth external surface to prevent dust and dirt buildup while molded internal apertures give precise positioning and also provide protection from ambient light interference.



- Ambient light and dust protection.
- Lead spacing available at .220", .300", or .320".
- .050" and .010" aperatures available.



SEMICONDUCTOR

ABSOLUTE MAXIMUM RATINGS (T ₄ = 25°C Unless (Otherwise Specified)
Storage Temperature	-40°C to + 85°C -40°C to + 85°C
Soldering: Lead Temperature (Iron) Lead Temperature (Flow)	
INPUT DIODE Continuous Forward Current Reverse Voltage Power Dissipation	
OUTPUT TRANSISTOR Collector-Emitter Voltage Emitter-Collector Voltage Collector Current Power Dissipation	

ELECTRICAL CHARACTERISTICS (T _A = 25°C Unless Otherwise Specified)							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS	
INPUT DIODE Forward voltage	V _F	_		1.70	v	l _F = 20 mA	
Reverse Leakage Current	l _n	_		100	μA	V _R = 2.0 V	
OUTPUT TRANSISTOR Emitter-Collector Breakdown	BV _{ECO}	5			v	$I_{\rm E} = 100 \ \mu {\rm A}, {\rm Ee} = 0$	
Collector-Emitter Breakdown	BV _{CEO}	30			V	$I_c = 1.0 \text{ mA}, \text{ Ee} = 0$	
Collector-Emitter Leakage	CEO			100	nA	$V_{ce} = 10.0 V, Ee = 0$	
COUPLED On-State Collector Current	I _{C(ON)}	See selection guide page 3.		mA	$I_{\rm F} = 20$ mA, $V_{\rm CE} = 5$ V		
Saturation Voltage	V _{CE(SAT)}	_		0.40	V	$I_{\rm F}$ = 20 mA, $I_{\rm C}$ = 0.1 mA	

NOTES

Derate power dissipation linearly 1.67 mW/°C above 25°C.
RMA flux is recommended.
Methanol or Isopropanol alcohols are recommended as cleaning agents.
Soldering iron tip 1⁄4″ (1.6 mm) from housing.



PART NUMBER	LEAD SPACING	APER	TURES	I _{C(ON)}		
		LED	SENSOR	MIN	MAX	
QVB11123	.220″	0.050"	0.010"	0.20	_	
QVB11124	.220″	0.050″	0.010″	0.50		
QVB11223	.300″	0.050"	0.010″	0.20	_	
QVB11224	.300″	0.050″	0.010"	0.50	_	
QVB11323	.320″	0.050"	0.010"	0.20		
QVB11324	.320″	0.050″	0.010"	0.50	_	
QVB11133	.220″	0.050"	0.050″	0.50	_	
QVB11134	.220″	0.050″	0.050″	1.00	—	
QVB11233	.300″	0.050″	0.050"	0.50	_	
QVB11234	.300″	0.050"	0.050″	1.00	—	
QVB11333	.320″	0.050"	0.050″	0.50	100	
QVB11334	.320″	0.050″	0.050"	1.00	_	
QVB21113	.220″	0.010"	0.010"	0.10	_	
QVB21114	.220″	0.010″	0.010"	0.20	—	
QVB21213	.300″	0.010″	0.010″	0.10		
QVB21214	.300″	0.010"	0.010″	0.20	_	
QVB21313	.320″	0.010"	0.010"	0.10	_	
QVB21314	.320″	0.010"	0.010"	0.20	—	



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